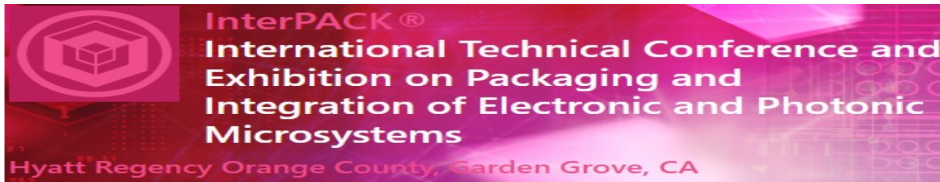

Call for InterPACK2022 Papers for a Special Issue to be published by the ASME Journal of Electronic Packaging

Editorial Team: Dr. Jin Yang (Samsung Semiconductor), Prof. Sukwon Choi (Pennsylvania State University) and TBD.

InterPACK is a premier international forum for the exchange of state-of-the-art knowledge in research, development, manufacturing, and applications of electronic packaging and micro/nano-electromechanical systems. It is also the flagship conference of the ASME Electronic and Photonic Packaging Division (EPPD). The Journal of Electronic Packaging (JEP) publishes papers that use experimental and theoretical (analytical and computer-aided) methods, approaches, and techniques to address and solve various mechanical, materials, thermal, and reliability problems encountered in the analysis, design, manufacturing, testing, and operation of electronic and photonics components, devices, and systems.

Authors are invited to submit their manuscripts by **March 31st 2023**, **revised from** their original conference papers to be considered for the Special Issue. These papers will be evaluated by the Associate and Guest Editors and go through the standard JEP review process. The presentation-only contributors are also invited to submit full-length manuscripts that represent their work. The manuscripts should clearly indicate the InterPACK2022 paper number on the first page. During the submission process, please select the option for submission to this InterPACK Special Issue. Please submit your manuscripts through https://journaltool.asme.org/home/.

The aim of this JEP special issue is to publish outstanding papers from the diverse technical tracks of InterPACK 2022. Please note the manuscript shall meet the following requirements to be considered by this special issue,

1. The special issue is targeted to publish honorary-quality papers from InterPACK2022, that extend from the conference proceedings.
2. Please revise the original InterPACK2022 conference paper with new contents to meet a **similarity requirement of <50%.**
3. The submission should be directly revised from the InterPACK2022 paper or technical presentation. Please include the original InterPACK paper in the appendix of your submission to this special issue.

Should you have any questions, please contact Dr. Jin Yang at jin1.yang@ieee.org.

Important Dates	
Electronic manuscript submission	March 31st, 2023
Target publication date of the Special Issue	December 2023